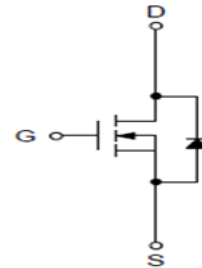


POWER MOSFET

Features

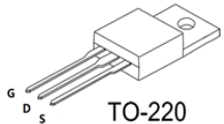
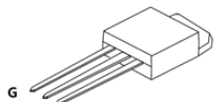
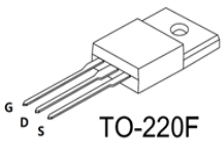
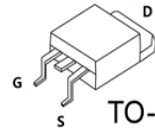
- 60V,50A N-Channel MOSFET
- $R_{DS(on)(typ.)}=6m\ \Omega$ @ $V_{GS}=10V$
- High ruggedness
- Fast switching
- 100% avalanche tested
- Exceptional dv/dt capability



N-Channel MOSFET

Applications

- Switching application
- Motor drive

SF50N06P	 TO-220	SF50N06I	 TO-251
SF50N06F	 TO-220F	SF50N706D	 TO-252

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 25	V
I_D	Continuous Drain Current($T_C=25\ ^\circ C$)	50	A
	Continuous Drain Current($T_C=100\ ^\circ C$)	40	A
I_{DM}	Pulsed Drain Current(Note 1)	200	A
EAS	Single Pulsed Avalanche Energy(Note 2)	100	mJ
P_D	Maximum Power Dissipation ($T_C=25\ ^\circ C$)	70	W
	Maximum Power Dissipation ($T_C=100\ ^\circ C$)	34	W
T_J	Operating Junction Temperature Range	-55 to +175	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to +175	$^\circ C$

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Starting $T_J=25\ ^\circ C, L=1.0mH, R_G=50\ \Omega, I_D=37A, V_{GS}=10V$

Thermal data

Symbol	Parameter	Max.	Units
$R_{th\ J-C}$	Thermal Resistance, Junction to case	2.1	$^{\circ}C/W$

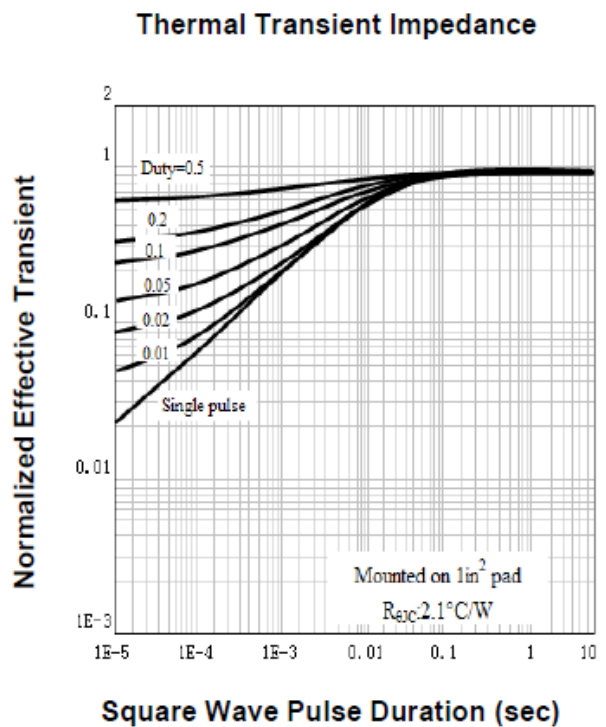
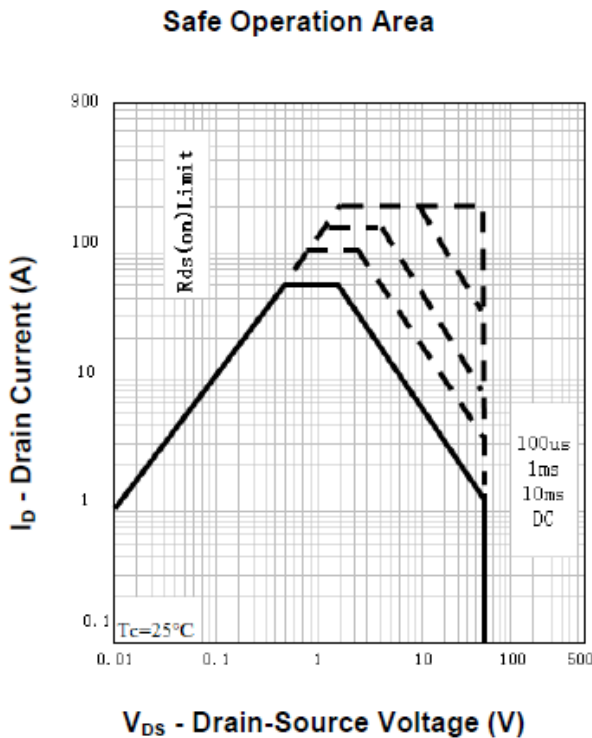
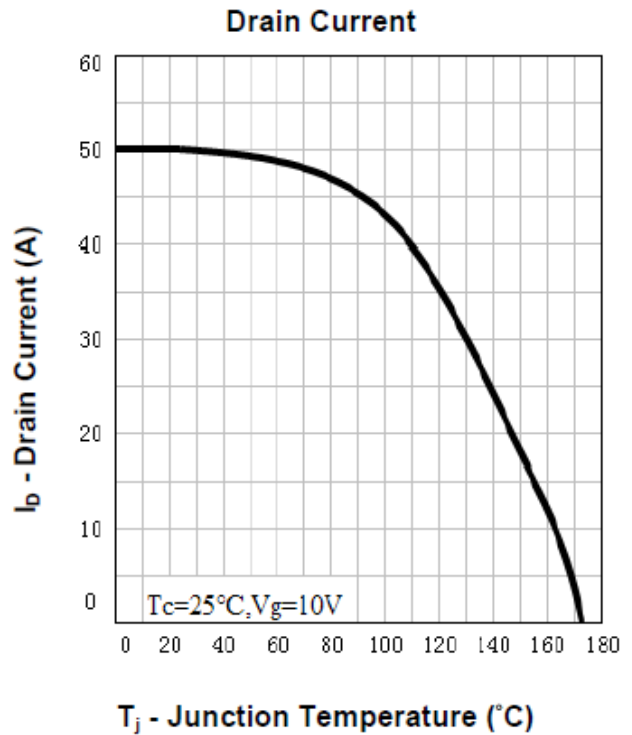
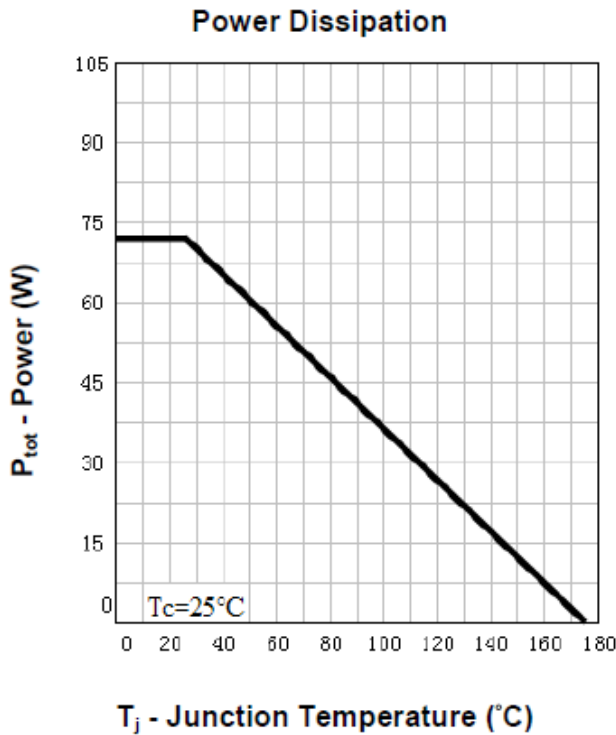
Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
I_{DSSS}	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V$			1	μA
I_{GSS}	Gate Leakage Current, Forward	$V_{GS}=25V, V_{DS}=0V$			100	nA
	Gate Leakage Current, Reverse	$V_{GS}=-25V, V_{DS}=0V$			-100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V
$R_{DS(on)}$	Collector-Emitter Saturation Voltage	$V_{GS}=10V, I_D=25A$		6	10	m Ω
gfs	Forward Transconductance	$V_{DS}=15V, I_D=30A$		18		S
Q_g	Total Gate Charge	$V_{DD}=30V$ $V_{GS}=10V$ $I_D=25A$		40		nC
Q_{gs}	Gate-Source Charge			10		nC
Q_{gd}	Gate-Drain Charge			9		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30V$ $V_{GS}=10V$ $I_D=25A$ $R_G=4.7\Omega$	-	10	-	ns
t_r	Turn-on Rise Time		-	86	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	34	-	ns
t_f	Turn-off Fall Time		-	26	-	ns
C_{iss}	Input Capacitance	$V_{DS}=30V$ $V_{GS}=0V$ $f=1MHz$	-	1650	-	pF
C_{oss}	Output Capacitance		-	380	-	pF
C_{rss}	Reverse Transfer Capacitance		-	165	-	pF
R_{Gint}	Integrated gate resistor			1.6		Ω

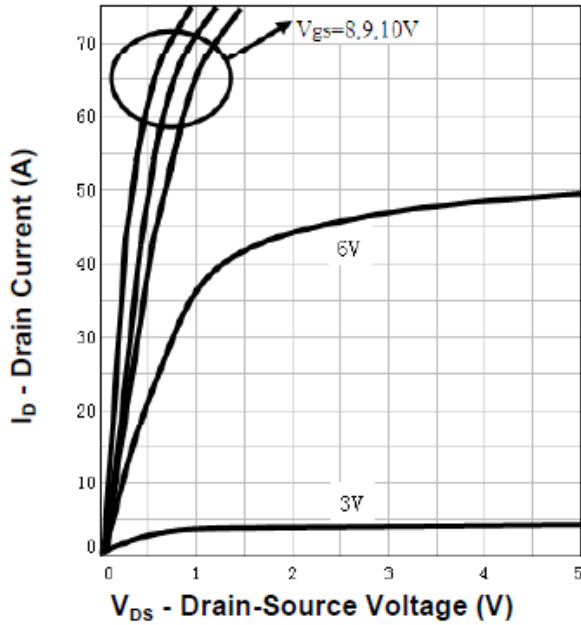
Source-Drain Ratings and Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage	$V_{GS}=0V, I_S=20A$	-		1.2	V
I_S	Continuous Diode Forward Current				50	A
t_{rr}	Reverse Recovery Time	$V_{DD}=25V, I_S=25A$ $dI_F/dt=100A/\mu s$	-	32		ns
Q_{rr}	Reverse Recovery Charge		-	40		nC

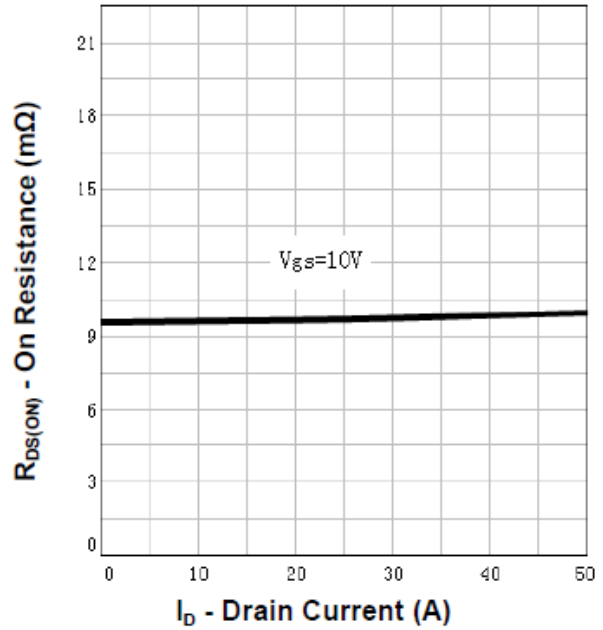
Typical Characteristic



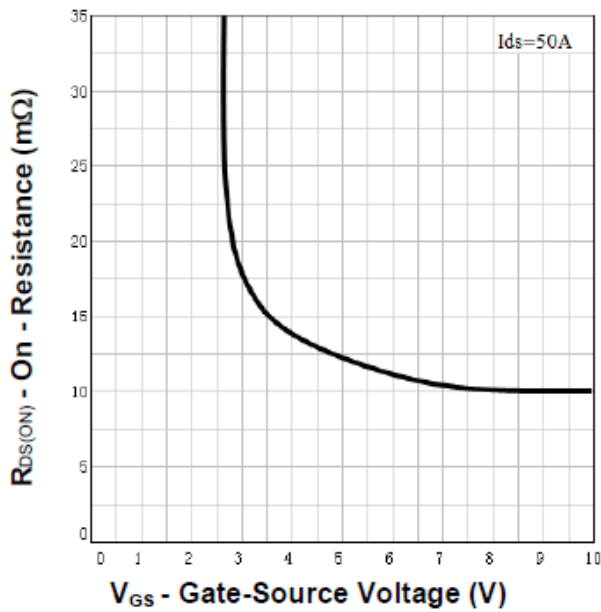
Output Characteristics



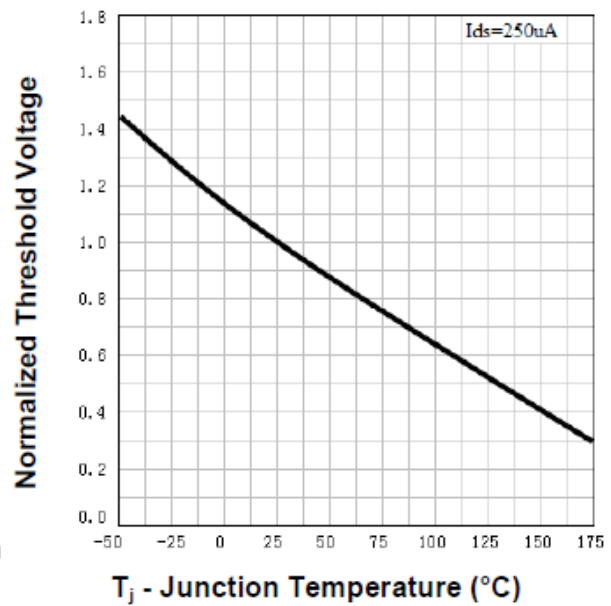
Drain-Source On Resistance



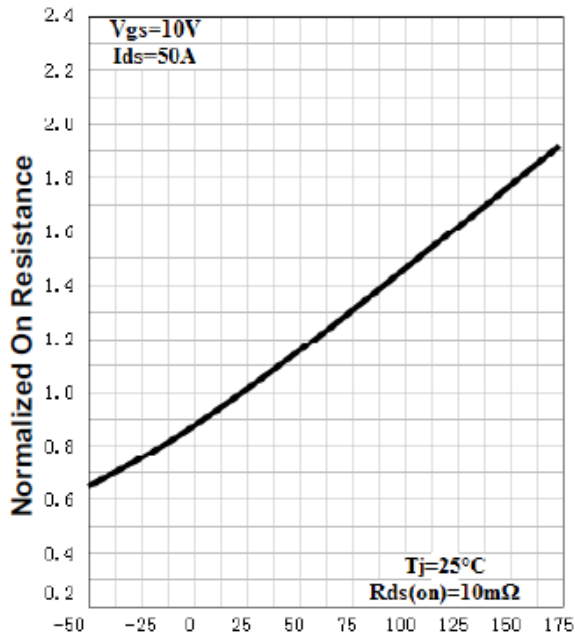
Drain-Source On Resistance



Gate Threshold Voltage

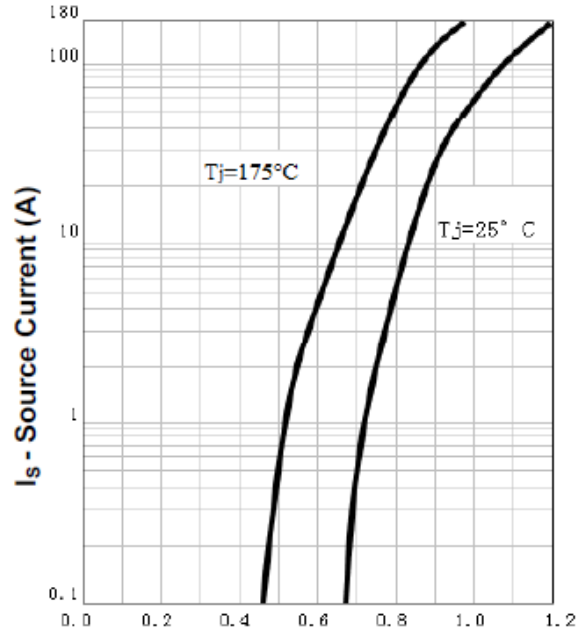


Drain-Source On Resistance



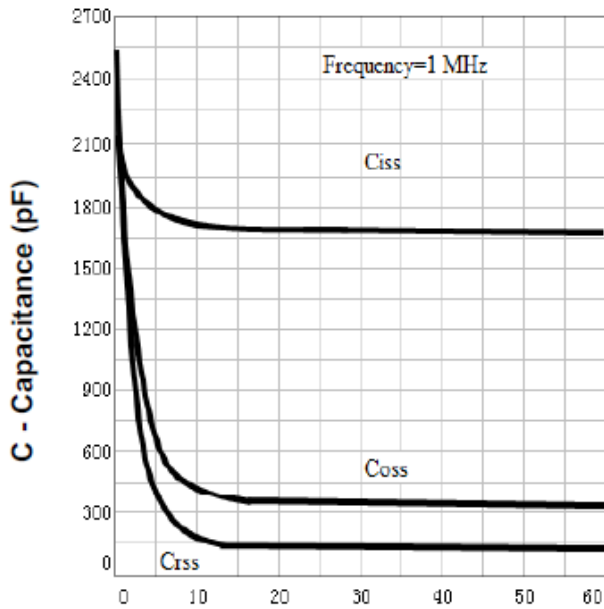
T_j - Junction Temperature (°C)

Source-Drain Diode Forward



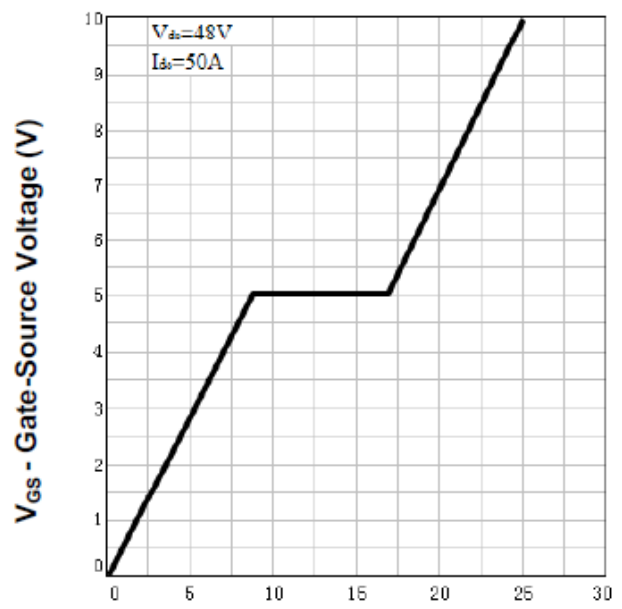
V_{SD} - Source-Drain Voltage (V)

Capacitance



V_{DS} - Drain-Source Voltage (V)

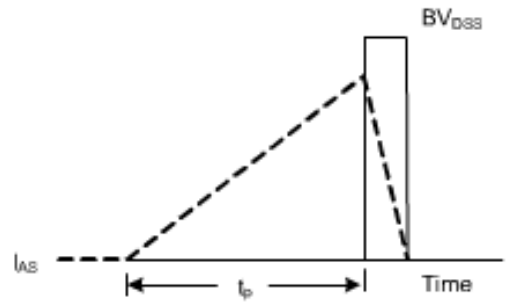
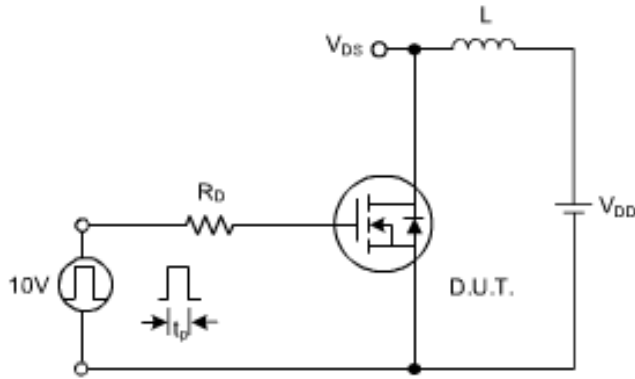
Gate Charge



Q_G - Gate Charge (nC)

Test Circuits

Avalanche test circuits and waveforms



Gate charge test circuits and waveforms

